

Technical Information Sheet

1. Name of technology	Reclaiming (recycling) of dummy/monitor wafers (200 and 300 mm) for semiconductor manufacturing equipment
2. Type of technology	This technology makes it possible to reclaim dummy/monitor wafers that have been used in semiconductor manufacturing processes. Minimizing polishing removal increases the number of times reclaimed wafers can be used, thereby reducing purchase of new wafers.
3. Description of technology	<p>[Objective and application of the technology] In this technology, our proprietary chemicals are utilized to remove films adhering to dummy/monitor wafers used in semiconductor manufacturing processes to enable the reclaiming of wafers that previously were discarded. In addition, reducing the stock removal of surface damage by fine surface polishing increases the number of times reclaimed wafers can be used. Also, irreclaimable wafers are recycled for solar cell wafers and Si materials.</p> <p>[Characteristics of the technology]</p> <div data-bbox="438 862 1372 1142" data-label="Diagram"> <pre> graph LR A[Used wafer] --> B[Regeneration treatment (film-stripping and polishing)] B -- Reclaiming --> C[Reclaimed wafer] B -- Recycling --> D[To be sold as solar-cell wafers or Si materials] </pre> </div> <p>(1) Analysis of films adhering to wafers and development of our proprietary high-selectivity etching chemicals. (2) Reduction of stock removal polishing (using the single-wafer polishing technology we have designed). (3) Wafers are returned in a short turn-around time (minimizing your inventory of dummy/monitor wafers).</p> <p>[Delivery record] Customers: Semiconductor manufacturers in Japan, China, and Taiwan</p> <p>[Price and other inquiries] Person in charge: Nobukiyo Konishi Planning and Sales Department, Wafer-Techno Business Division, Shinryo Corporation TEL: +81-93-643-2778 E-mail: 6008513@shinryo-gr.com</p>
4. Classification of technology	
(1) Applicable fields	Recycling (materials)
(2) Target waste	Electronic products
(3) Services provided	Other

Objective, application, characteristics, delivery record, and price of technology

5. Countries to which this technology can be provided	Mainly Japan and Asia (China, Taiwan, South Korea, and Singapore), plus other countries worldwide.
6. Keywords	Wafer, recycling, reclaiming, polishing, cleaning, dummy, monitor
7. Contact information	Please refer to [Price and other inquiries] under item 3.